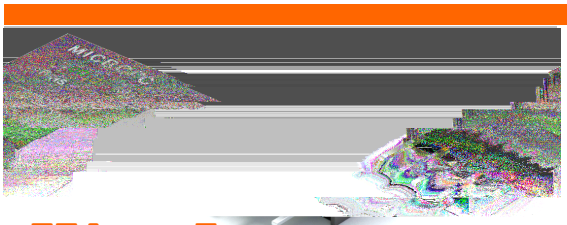


FEA E

- Small foo prin
- SIP6 package
- Tempera re range: -40℃ +85℃
- 1KVDC isola ion
- No Hea sink req ired
- No e ernal componen req ired
- In ernal SMD Cons r c ion
- Ind s r s andard pino
- RoHS Compliance

① ② ③ ④ ⑤ ⑥ ⑦ ⑧

①Prod c Series ②Inp Vol age
③The 1s O p Vol age ④The 2nd O p Vol age
⑤Fi ed Inp ⑥Nega ion o p
⑦Mini SIP Package ⑧Ra ed Po er

The D-XNM-1W Series are speciall designed for applica ions here a gro p of polar po er s pplies are isola ed from he inp po er s ppl in a dis rib ed po er s ppl s s em on a circ i board.
These prod c s appl o:
1) Where he ol age of he inp po er s ppl is fi ed (ol age aria ion 10%);
2) Where isola ion is necessar be een inp and o p (isola ion ol age 1000VDC);
3) Where he reg la ion of he o p ol age and he o p ripple noise are no demanding.
S ch as:p rel digi al circ i s, ordinar lo freq enc analog circ i s,and IGBT po er de ice dri ing circ i s.

D C G AM

Par N mber	Inp		O p			Efficienc (%,T p)
	Vol age(VDC)		Vol age (VDC)	C rren (MA)		
	Nominal	Range		Ma	Min.	
D030505XNM-1W	3.3	2.97-3.63	5	100	10	70
D050303XNM-1W	5	4.5-5.5	3.3	152	15	62
D050505XNM-1W	5	4.5-5.5	5	100	10	71

C MM ECIFICA I

S orage h midi range				95	%
Opera ing empera re		-40		85	℃
S orage empera re		-55		125	
Lead empera re	1.5mm from case for 10 seconds			300	
Temp. rise a f ll load			15	25	
Shor circ i pro ec ion*				1	S
Cooling		Free air con ec ion			
Case ma erial		Plas ic(UL94-V0)			
MTBF		3500			K ho rs
Weigh			1.4		g

*S ppl ol age m s be discon in ed a he end of shor circ i d ra ion.

I LA I ECIFICA I

Isola ion ol age (Vin/Vo)	Tes ed for 1 min e and 1mA ma	1000			VDC
Isola ion ol age (Vo1/Vo2)	Tes ed for 1 min e and 1mA ma	1000			VDC
Isola ion resis ance (Vin/Vo)	Tes a 500VDC	1000			M
Isola ion resis ance (Vo1/Vo2)	Tes a 500VDC	1000			M
Isola ion capaci ance(Vin/Vo)			30		pF
Isola ion capaci ance(Vo1/Vo2)			30		pF

A LICA I E

To ens re his mod le can opera e efficien l and reliabl , D ring opera ion, he minim m o p load co ld no be less han 10% of he f ll load . If he ac al o p po er is er small , please connec a resis or i h proper resis ance a he o p end in parallel o increase he load , or se o r compan prod c s i h a lo er ra ed o p po er.

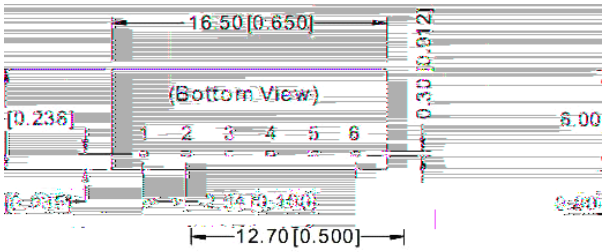
If o an o f r her decrease he inp /o p ripple , an "LC" fil ering ne ork ma be connec ed o he inp and o p ends of he DC/DC con er er, see (Fig re 1).

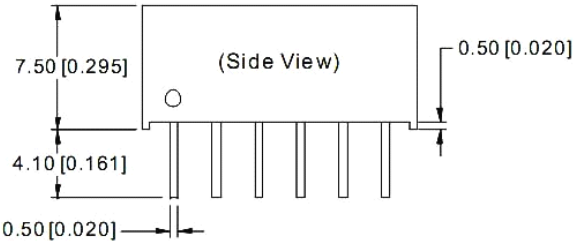
I sho ld also be no ed ha he ind c ance and he freq enc of he "LC" fil ering ne ork sho ld be s aggered i h he DC/DC freq enc o a oid m al in erference. Ho e er , he capaci ance of he o p fil er capaci or m s be proper. If he capaci ance is oo big , a s ar p problem migh arise. For e er channel of o p , pro ided he safe and reliable opera ion is ens red , he recommended capaci ance of i s fil er capaci or sees (Table 1).

The simples de ice for o p ol age

LI E DIME I & F I DE AIL

MECHA ICAL DIME I





No e:

Uni :mm[inch]

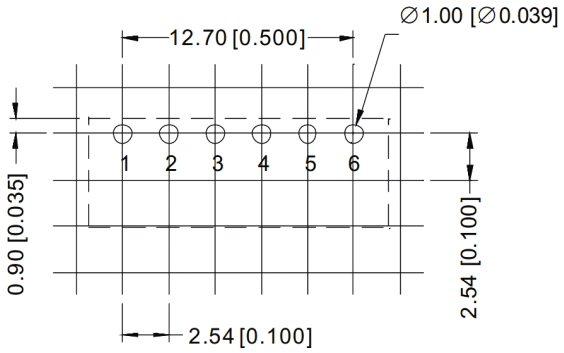
Pin sec ion olerances: 0.10mm[0.004inch]

General olerances: 0.25mm[0.010inch]

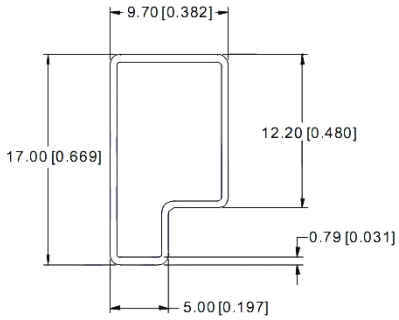
I POUT PRINT DE TAILS

Pin	Function
1	Vin
2	GND
3	0V1
4	Vo1
5	0V2
6	Vo2

EC MME DED F I



BE LI E DIME I



No e:

Uni :mm[inch]

General olerances: 0.50mm[0.020inch]

L=530mm[20.866inch] T be Q an i : 30pcs

L=220mm[8.661inch] T be Q an i : 11pcs

Professional Power Module

Microdc Professional Po er Mod le,Inc.

Tel:0086-20-86000646 E-mail: ech@microdc.cn

Websi e:h p:// .microdc.cn

RoHS

This series is compa ible i h RoHS soldering s s ems i h a peak a e solder empera re of 300 C for 10 seconds.
The pin ermina ion finish on he SIP package pe is Tin Pla e, Ho Dipped o er Ma e Tin i h Nickel Prepla e. The DIP pes are Ma e Tin o er Nickel Prepla e. Bo h pes in his series are back ard compa ible i h Sn/Pb soldering s s ems.

REACH

This series has pro en ha his prod c does no con ain harmf l chemicals, i also has harmf l chemical s bs ances hro gh he regis ra ion, inspec ion and appro al.